

Electronic Components Assembly Materials

EMI/RFI SHIELDING OF RIBBON CABLES AND FLEX CIRCUITS

SILVER INKS

Product #	Sheet Resistivity (ohms/sq/mil)	Curing Technique	Comments
102-05F	0.019	Thermal	Flexible, screen printable, temperature and chemical resistant.
105-43	0.019	Thermal	Flexible, sprayable concentrate, temperature and chemical resistant.
117-48	0.040	Thermal	Flexible, pad printable, temperature and chemical resistant.
120-07	0.010	Thermal	Extremely flexible. Suitable for EMI/RFI shielding of insulated wires/cables. Screen printable as is, or dilute for dipping or spraying.
118-41	0.010	Thermal	Excellent adhesion to Kapton and other materials where higher temperature is required. Suitable for EMI/RFI shielding of insulated wires/cables. Screen printable. Resistant to abrasion and scratching.

DIELECTRIC INKS

Product #	Dielectric Strength (volts/mils)	Curing Technique	Comments
113-48	525	Thermal and UV	Exceptional flexibility, screen printable.
116-20	365	UV	Translucent clear color. Screen printable, solvent resistant, flexible dielectric for use with products 102-05F, 104-18, 105-43, 116-19, 118-09 A/B and 120-07.
120-36	365	UV	Same as above, except translucent blue color.
123-40	365	UV	Same as above, except opaque blue color.
123-43	365	UV	Same as above, except translucent green color.
111-27	1300	Thermal	High dielectric strength, sprayable concentrate.
118-02	1300	Thermal	High dielectric strength, pad printable.

ENCAPSULATING MATERIALS

Product #	Volume Resistivity (ohms-cm)	Viscosity (cps) @ 25°C	Viscosity (cps) @ 50°C	Comments
108-50	1 X 10 ¹⁴	100,000 - 160,000	30,000 - 50,000	Exceptional resistance to thermal cycling. Low stress, low shrink potting compound and adhesive. Ideal for stress sensitive substrates.
110-18	1 X 10 ¹⁵	10,000		Cures at low temperatures with minimum amount of exotherm, releases air rapidly, resulting in smooth pinhole free surface. Useful for bonding and potting of dissimilar materials requiring Class "B" service temperature rating.
113-20	1 X 10 ¹⁵	45,000 - 75,000		Useful for potting dissimilar materials requiring Class "H" service temperature rating. Higher temperature version of 108-50.
109-12	1 X 10 ¹⁴	500,000	60,000	Exceptional resistance to thermal cycling. Bonds dissimilar materials requiring Class "F+" service temperature rating. More thermally conductive version of 108-50.

POTTING COMPOUNDS

Product # Part A	Product # Part B (Hardener)	Mix Ratio by Weight	Viscosity (cps)	Working Life @21°C	Comments
F940A	F940B	100:12	2,750	30 mins.	Black, flame-out, epoxy potting and encapsulating compound. Low viscosity, self de-aerating, thermally conductive. Room temperature cure.
F940A	B-187	100:3	3,000	> 4 hours	Low viscosity with long pot life. Requires mild heat cure.
F947A	F947B	100:12	5,000	30 mins.	Room temperature, improved heat resistance. Other properties similar to F940A/B.
F947A	B-187	100:3	7,000	> 4 hours	Excellent heat resistance, extended pot life. Requires mild heat cure.
102-11A	102-11B	100:12	6,000	30 mins.	Crack resistant, black, flame-out, epoxy compound. Room temperature cure, improved resistance to thermal cycling. Other properties similar to F947A/B.
102-11A	B-187	100:3	7,000	> 4 hours	Excellent resistance to thermal shock, longer pot life. Requires mild heat cure.
102-12A	102-12B	100:9	15,000	30 mins.	Thermal cycle resistant, black, epoxy compound. Room temperature cure, improved crack resistance. High thermal conductivity.
102-12A	B-187	100:2.5	16,000	> 4 hours	Same as above, but extended pot life; better resistance to thermal cracking.
113-33A	113-33B	100:15	380,000	> 30 mins.	Crack resistant, black, flame-out, glob top epoxy. Non sag encapsulant.

PLEASE CONTACT US FOR OTHER MARKET SPECIFIC PRODUCT SELECTOR GUIDES



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